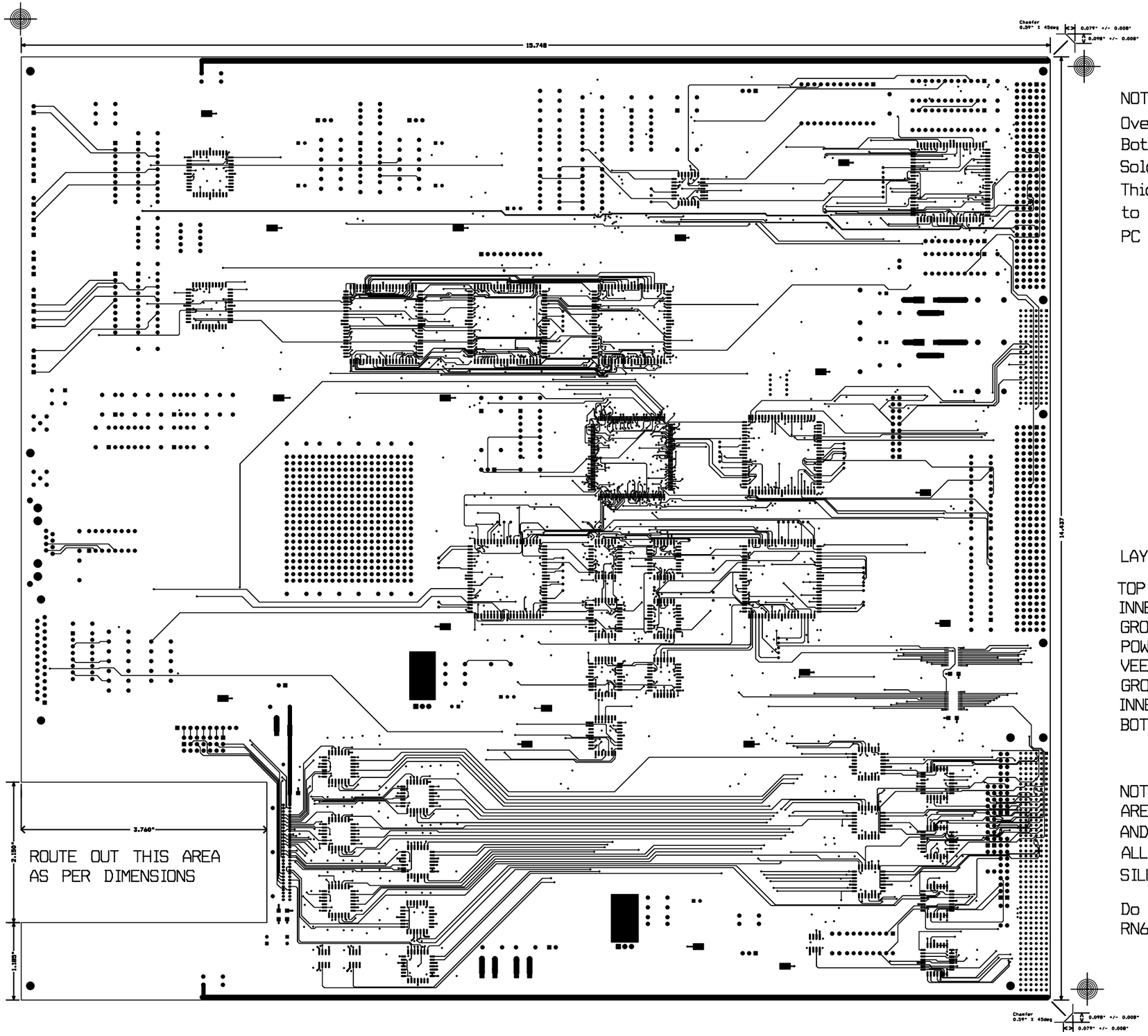
FERMILAB FIB FANOUT REV.B

TOP



NOTE:

Overall Board Thickness = .093" +/- .008"
Both Top and Bottom Edge of Board on the Solder Side to be Milled to .063" +/- .008" Thickness .098" +/- .008" in from each Edge to Allow for Card Edge Guide Thickness.
PC Board Dimensions are in MILS

LAYER STACKUP:

TOP TRACE LAYER
INNER TRACE LAYER 1
GROUND PLANE
POWER PLANE
VEE POWER PLANE
GROUND PLANE
INNER TRACE LAYER 2
BOTTOM TRACE LAYER

NOTE: ALL TRACE LAYERS ARE 0.005" TRACE WIDTH AND SPACING, 1.0oz COPPER ALL LAYERS. TOP AND BOTTOM SILKSCREENS.

Do Not Install:
RN6, RN7, RN8, RN9, RN10, RN11

FERMILAB FIB FANOUT REV.B

BOTTOM

FERMILAB FIB FANOUT REV.B

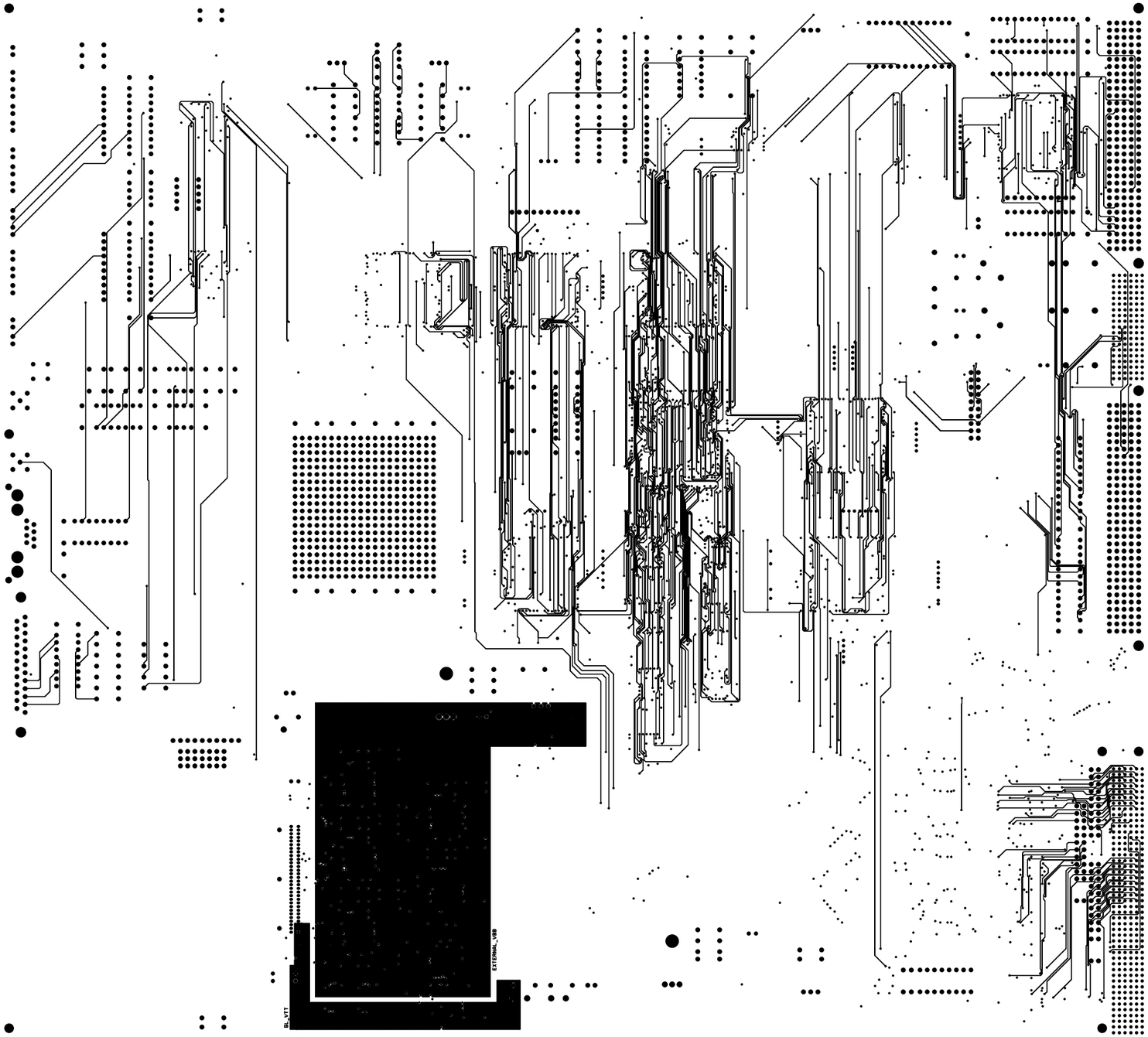
GND PLANE

FERMILAB FIB FANOUT REV.B

POWER PLANE

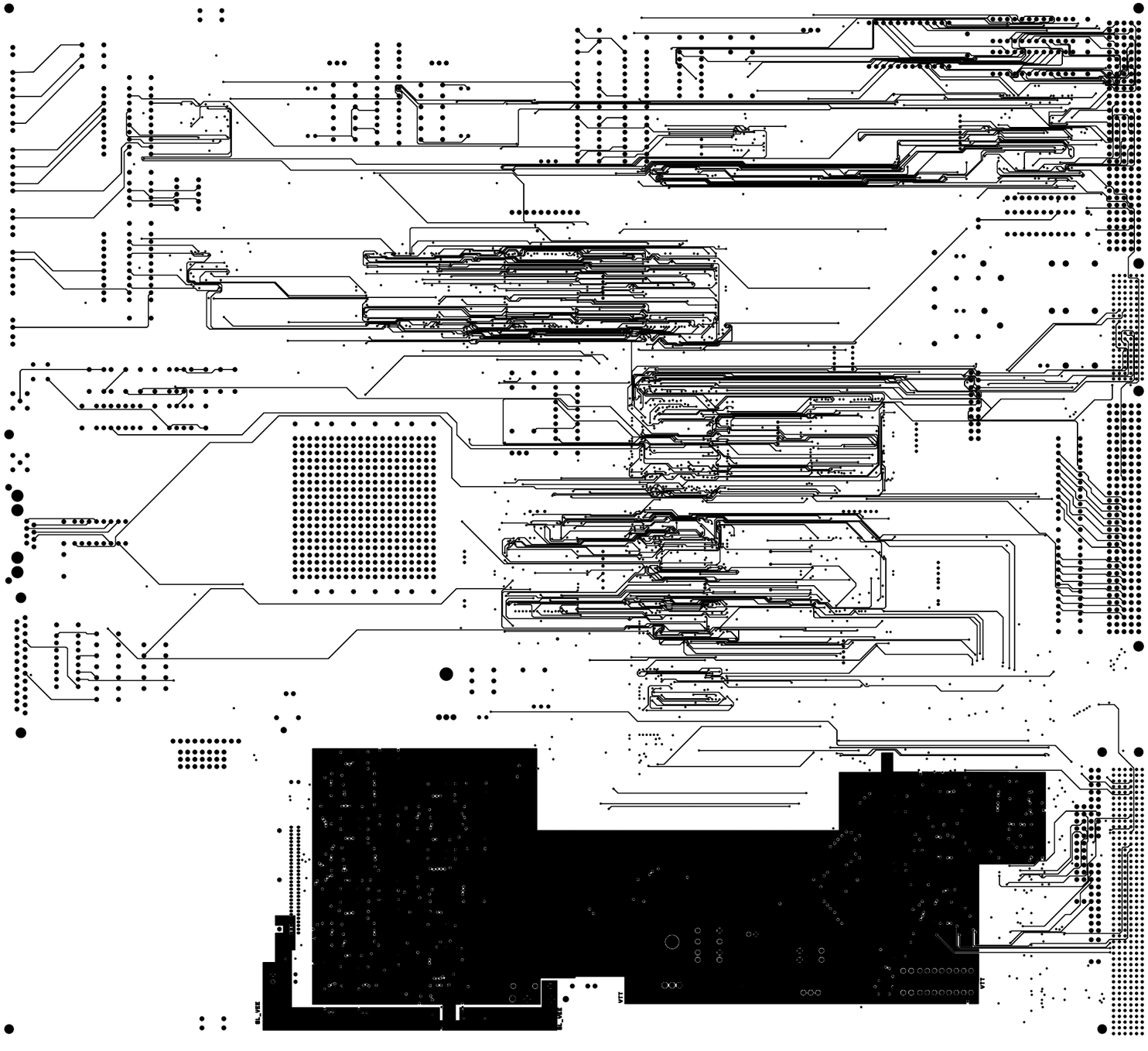
FERMILAB FIB FANOUT REV.B

INTERNAL 1



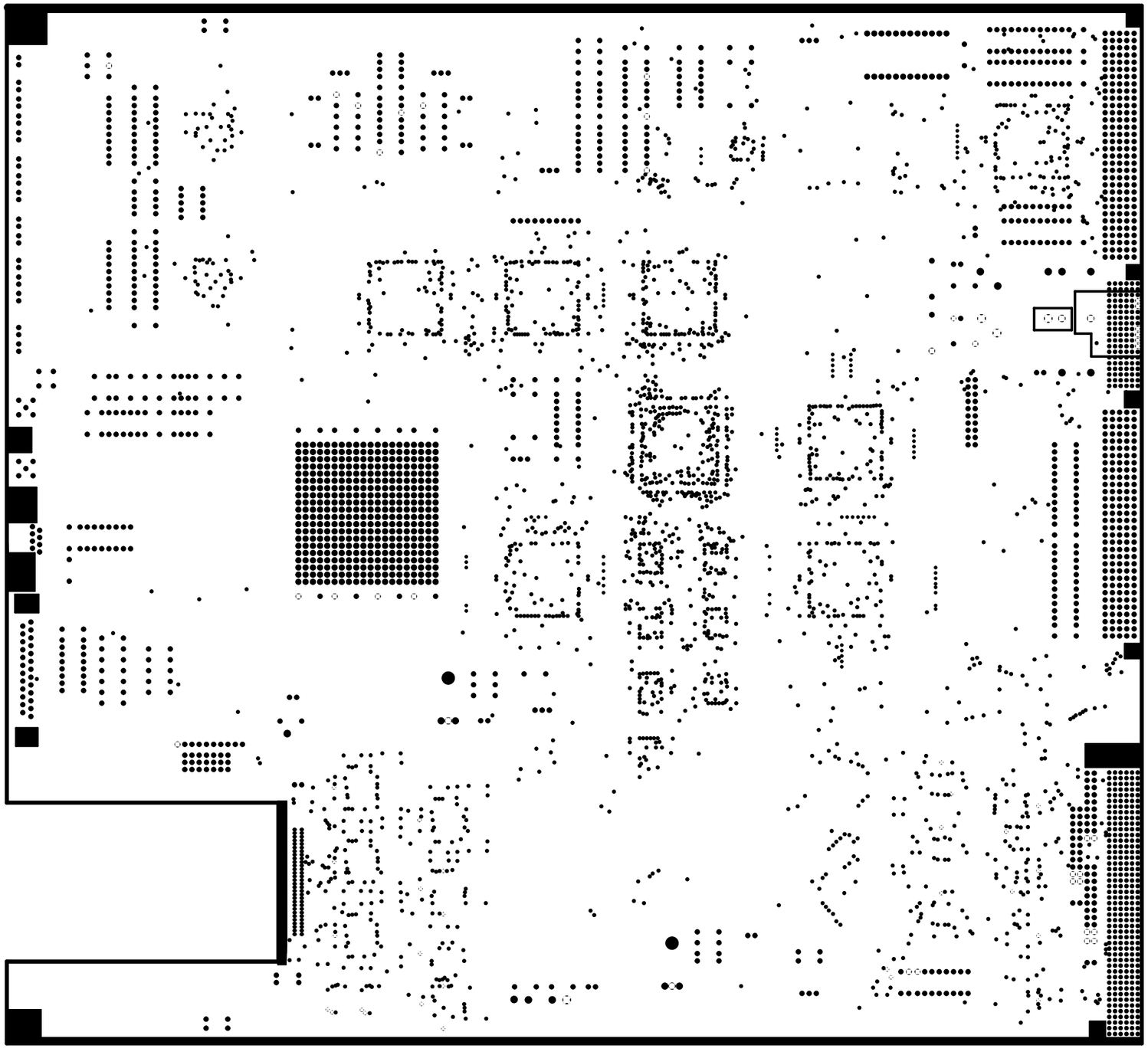
FERMILAB FIB FANOUT REV.B

INTERNAL 2



FERMILAB FIB FANOUT REV.B

VEE POWER PLANE



FERMILAB FIB FANOUT REV.B

SILKSCREEN TOP

SVX
FIB FANOUT
FERMILAB CD/ESE
REV. B 07/98
Board Design: J.T. Anderson
PCB Design: J. Chramowicz

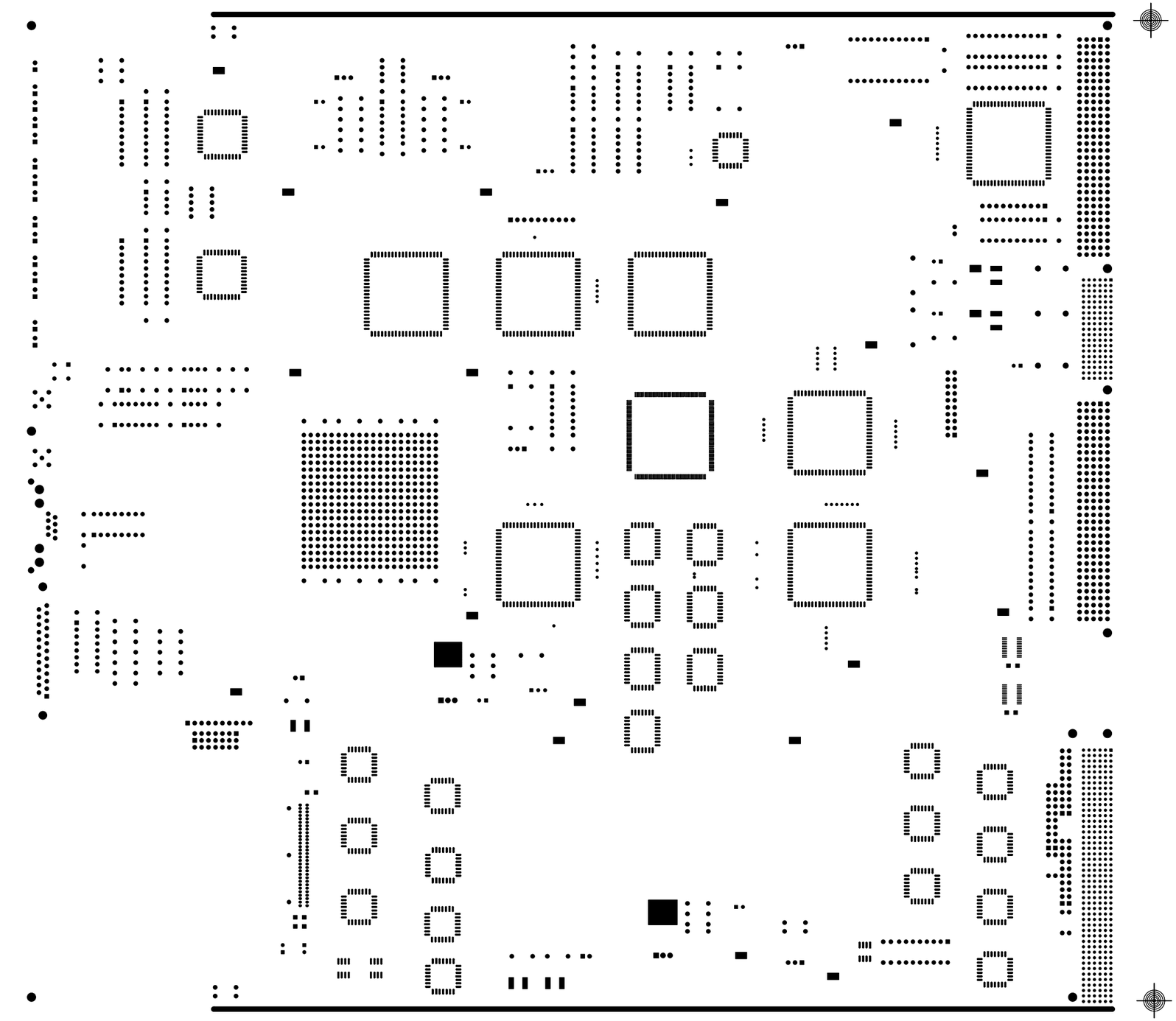
LED1 SLAVE
LED2 +3.3V PWR
LED3 -5 V PWR
D1 BL_VTT
LED4 J3_PWR
LED5 INITIALIZE
LED6 RUN
LED7 MODE FAULT
LED8 SRC CLOCK
LED9 LOCAL CLOCK
LED10 BLINK LOCKED
LED11 BLINK ERROR
LED12 FRT PWR LOW
LED13 TEST FIFO ACTIVE
LED14 ERROR
RESET PB1
LEMO1 RESET OUT
Front Panel Mount
LEMO2 Scope Trigger
J1 75174 U1 RN1 RS485 SRC Status Link
J4
Serial Number
Revision Level
IBP Programming Interface
LED Control Logic
LED Control 1
LED Control 2
Reset Circuitry
Voltage Comparators
ADC
Error Decoder 2 (Bits 2&3)
Error Latch
Error Decoder 1 (Bits 0&1)
Kludge Area
53Mhz Clock Distribution
Test & Error Fifo Control
Clock Control
Error Pipeline Comparator
+5 Volt Power
-5.2 Volt Power
P3 PWR
Analyzer Connection
VME Interface
NORMALLY INSTALLED
-2.10V Regulator
EXTERNAL VBB ADJ.
Do Not Install
Bourns 3299
TB1 LM3SCA
TB2 LM3SCA
P1
P0
P2
P3

FERMILAB FIB FANOUT REV.B

SILKSCREEN BOTTOM

FERMILAB FIB FANOUT REV.B

SOLDER MASK TOP

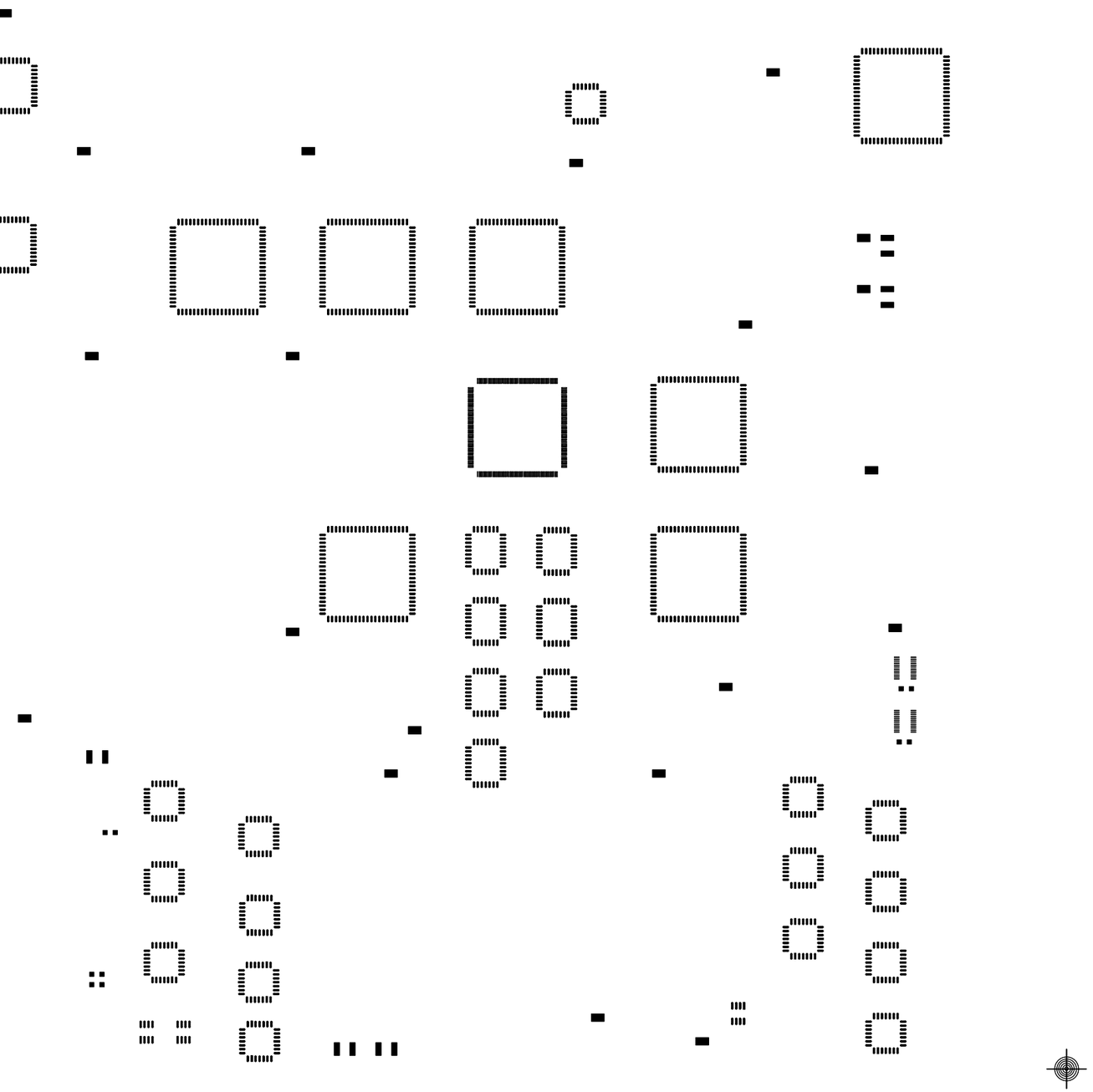


FERMILAB FIB FANOUT REV.B

SOLDER MASK BOTTOM

FERMILAB FIB FANOUT REV.B

SOLDER PASTE TOP

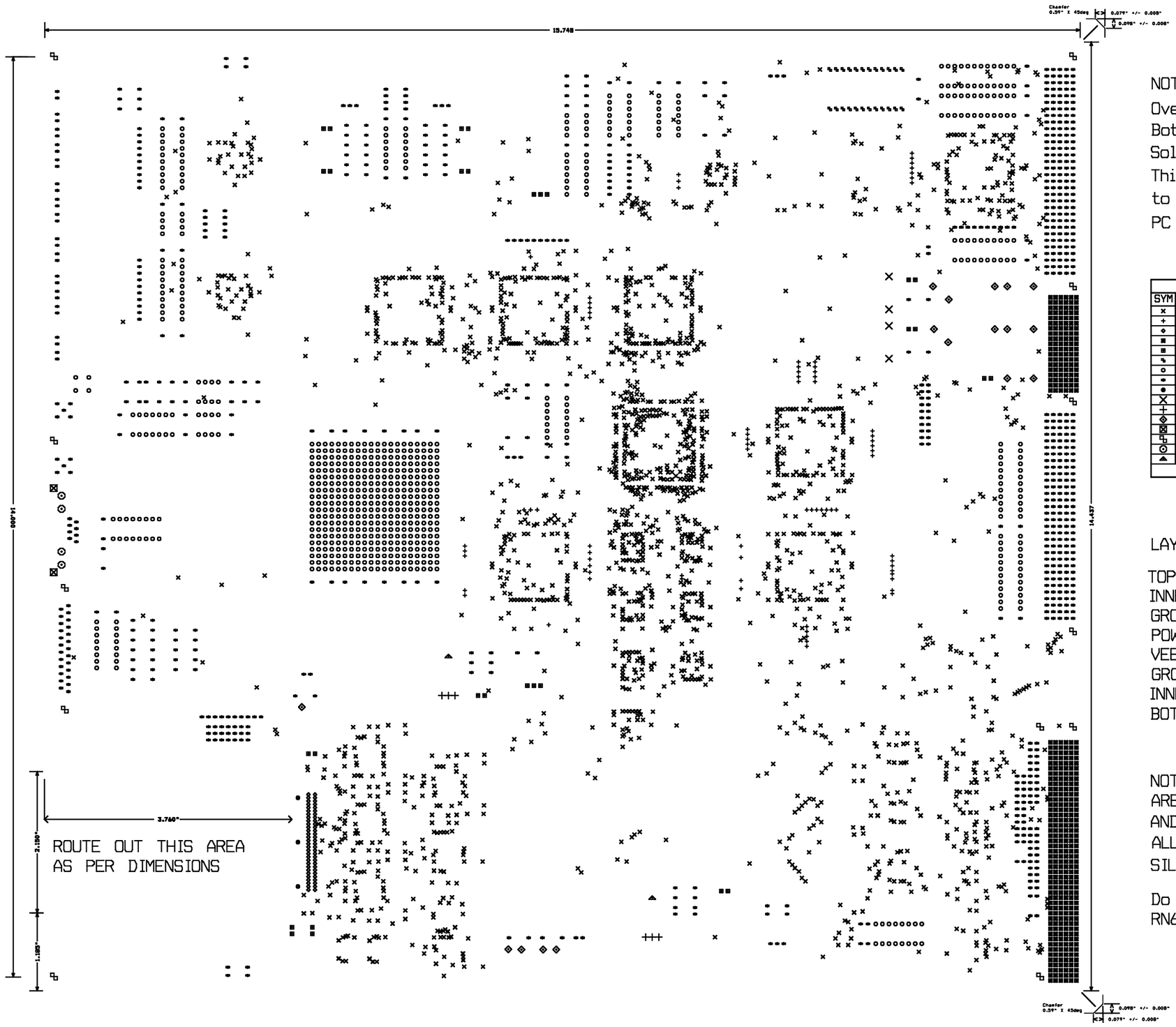


FERMILAB FIB FANOUT REV.B

SOLDER PASTE BOTTOM

FERMILAB FIB FANOUT REV.B

DRILL / FAB DRAWING



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HOLE LEGEND				
SYM	DIAM	TOL	QTY	NOTE
×	0.012		2201	
+	0.020		78	
◇	0.022		60	
■	0.025		396	
■	0.031		30	
◔	0.034		24	
○	0.035		724	
▪	0.038		805	
●	0.040		3	
╳	0.045		4	
┼	0.054		6	
◈	0.056		17	
⊠	0.062		2	
▭	0.110		12	
⊙	0.130		4	NON-PLATED
▲	0.147		2	NON-PLATED
TOTAL			4368	

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